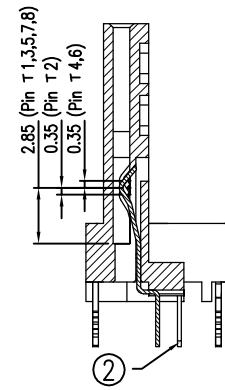
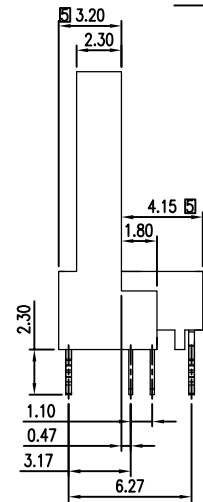
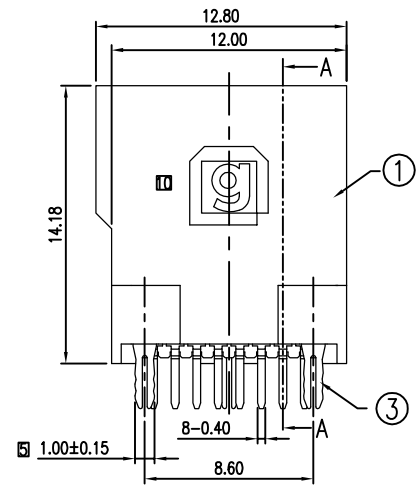
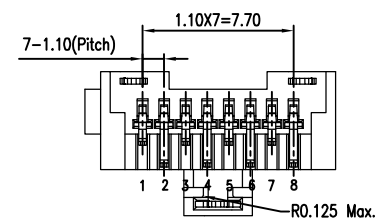
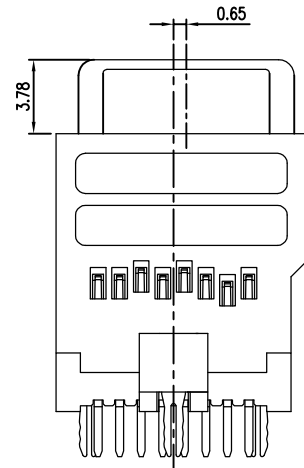


Recommended PCB layout



SECTION A-A



PinT	Description
1	DAT2
2	CD/DAT3
3	CMD
4	V _{DD}
5	CLK
6	V _{SS}
7	DAT0
8	DAT1

13	ADD PACKAGE OPTION	Terry	07/16/19'
12	CHANGE NOTES 3a, WAS -25°C	AXL	10/3/16'
11	MODIFY TOLERANCE	Terry	07/21/10'
10	ADD LOGO	Terry	07/07/10'
9	ADD FILLET	Terry	05/27/10'
8	ADD CHAMFER	Terry	05/25/10'
7	MODIFY DRAWING	Terry	05/14/10'
6	CONTACT PLATING	Terry	05/04/10'
5	MODIFY BOARD LOCK	Terry	04/29/10'
4	MODIFY BOARD LOCK	Terry	04/27/10'
3	MODIFY DRAWING	Terry	04/22/10'
REV.	ECN NO.	NAME	DATE

TOLERANCE	
LINEAR	ANGLES
X.±0.50	X°.±3°
.X±0.40	.X°±3°
.XX±0.30	.XX°±3°
.XXX±0.15	.XXX°±3°

GENESIS
TECHNOLOGY, INC
A Genesis Electro-Mechanical Company

Chung-Yang Rd.
Tu-Cheng City 7F, No. 191, Sec. 2
Taipei Hsien, Taiwan

APPD: _____ MAT'L: _____
CHKD: Terry FINISH: _____
DRWN: Terry Q'TY: _____

TITLE: MICRO SD CARD VERTICAL DIP TYPE			
PART NO. MSDV-2008-AK*0*01			
DWG NO. GTi10-25051			
	UNITS mm	SCALE NONE	SHEET 10F2
			REV 13

2] Notes:

1. Electrical:
 - a. Voltage Rating: 50VAC (r.m.s)
 - b. Current Rating: 0.5Amperes.
 - c. Insulation Resistance: 1000M ohms min. initial.
 - d. Dielectric Withstand Voltage: AC 500V/1 minute.
 - e. Contact Resistance: 100 m ohms max. initial;

2. Mechanical:
 - a. Material:
 - Contacts: Phosphor Bronze, T=0.2mm.
 - Board Lock: Brass, T=0.3mm.
 - Housing Flammability Rating: PBT, Black, UL94V-0
 - b. Plating:
 - Contacts: Gold plated 12u", Solder tail Tin plated 80u", 50u" nickel underplated overall.
 - Board Lock: Tin plated 80u", 50u" nickel underplated overall.
 - c. Durability: 10,000 Cycles.
 - d. Mating force: 25N Max.
 - Unmating force: 1.5N Min.
 - e. Solderability: More than 90% of solderable area
 - f. Soldering Profile: 260° for 10 seconds without remarkable deterioration.

3. Environmental:
 - a. Operating Temperature: -40°C to +85°C.
Storage Temperature: -40°C to +85°C.
 - b. Steady State Humidity: 90%~95% humidity on 40±2°C for 96hours.
 - c. Thermal Shock: 5 cycles of -55°C to 85°C.
 - d. Vibration Resistance: With dummy card applying DC 100mA,
Frequency: 10-2000Hz
Acceleration: 20m/s²
Sweep rate: 10-2000-10Hz in 5min.
Duration: 50min.(10 cyc)
Specimen to be excited along X,Y,and Z axes.(total:150min)
 - e. Impact Resistance: With dummy card applying DC 100mA,
Shock Waveform: Half sinewave
Acceleration: 490m/s²
Impact duration: 11msec.
9 total impacts delivered 3 each along X,Y, and Z axes. (total:9 impacts)
 - f. After test, contact resistance increase 40m ohms Max.

4. Compliance:
 - a. RoHS Compliance.

PART. NUMBER

MSDV-20 08 - A K * 0 * 01
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧

1. CONNECTOR:
MSDV: MICRO SD CARD.
2. TYPE
20: MICRO SD CRAD VERTICAL DIP TYPE
3. POSITIONS
08: 08 POSITION
4. INSULATOR MATERIAL
A: PBT
5. INSULATOR COLOR
K: BLACK
6. CONTACT PLATING
A: GOLD PLATING 12u'
7. SHIELD PLATING
0: NONE SHIELD
8. SHIELD PLATING
T: TRAY
R: TAPE REEL

PART NO.	MSDV-2008-AK*0*01	SHEET	REVISION
DWG NO.	GTi10-25051	2 OF 2	SEE SHEET 1